



17th International Workshop on Thermal investigations of ICs and Systems

Paris, France, 27-29 September 2011

General Chair
Bernard Courtois, CMP Grenoble, France

Vice General Chair
Marta Rencz, BUTE, Budapest, Hungary

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TUESDAY 27 SEPTEMBER 2011

- 08:00-10:00 **REGISTRATION**
- 10:00-10:10 **WELCOME ADDRESS**
Bernard Courtois, *CMP, Grenoble, France*
- 10:10-10:50 **INVITED TALK I: SYSTEM-LEVEL THERMAL-AWARE DESIGN OF 3D MULTI-PROCESSORS WITH INTER-TIER LIQUID COOLING**
David Atienza Alonso, *Ecole Polytechnique Federale de Lausanne (EPFL), Switzerland*
Chair: **Márta Rencz**, *Budapest Univ. of Technology and Economics, Hungary*
- 10 :50-11:50 **SPECIAL SESSION ON THE EUROPEAN RESEARCH GROUP ON NANOSCALE/THERMAL I**
Chair: **Peter Raad**, *South. Methodist Univ., USA*
- 10:50 HIGH RESOLUTION THERMAL IMAGING OF MICRO AND NANODEVICES BY SCANNING FLUORESCENCE MICROSCOPY
Lionel Aigouy, *ESPCI, Paris, France*
- 11:10 HETERODYNE IMAGING OF LOCALIZED HEATING IN PLASMONIC NANOANTENNAS
Sarah Y. Suck, S. Collin, N. Bardou, Y. De Wilde, G. Tessier, *ESPCI, Paris, France*
- 11:30 PHOTOTHERMAL CHARACTERIZATION OF SUBSTRATES AND COATINGS
Christ Glorieux, *KU Leuven, Belgium*
- 11 :50-12 :20 Coffee break
- 12:20-13:20 **SPECIAL SESSION ON THE EUROPEAN RESEARCH GROUP ON NANOSCALE/THERMAL II**
Chair: **Peter Raad**, *South. Methodist Univ., USA*
- 12:20 CHARACTERIZATION OF THE THERMOPHYSICAL PROPERTIES OF MATERIALS BY SCANNING THERMAL MICROSCOPY
Séverine Gomès, *CETHIL, INSA de Lyon, France*
- 12:40 NEW METHODS DEVELOPED FOR TESTING NANOCOMPOSITE THERMAL INTERFACE MATERIALS
Márta Rencz, *Budapest Univ. of Technology and Economics, Hungary*
- 13:00 [18] THERMAL INTERFACE MATERIALS BASED ON CARBON NANOTUBE CARPET AND POLYMERS
Sebastian Volz, Yuxiang Ni, *Ecole Centrale Paris, France*
- 13:30-15:00 Lunch
- 15:00-16:40 **THERMINATOR SPECIAL SESSION I**
Chair: **Vadim Tsoi**, *Huawei Technologies, Sweden*
- 15:00 THE THERMINATOR PROJECT: MIDWAY ACHIEVEMENTS AND PERSPECTIVES
Márta Rencz, *Budapest Univ. of Technology and Economics, Hungary*, **Salvatore Rinaudo, Enrico Macii**, *Politecnico di Torino, Italy*, **Salvatore Rinaudo, Giuliana Gangemi**, *STMicroelectronics, Italy*
- 15:20 [44] AN ANALOG BEHAVIORAL THERMAL MACRO-MODEL AIMED AT REPRESENTING AN ELEMENTARY PORTION OF A DISCRETE IGBT POWER DEVICE
Gaetano Bazzano, Daniela Grazia Cavallaro, Giuseppe Greco, *STMicroelectronics, Italy*
- 15:40 [59] SELF-HEATING EFFECTS IN NANO-SCALED MOSFETS AND THERMAL



Paris, France, 27-29 September 2011

vers. 22-Sep-11

AWARE COMPACT MODELS

Alex Burenkov, Jurgen Lorenz, *FhG Institute for Integrated Systems & Device Technology, Germany*

16:00 [7] 3D ELECTRO-THERMAL SIMULATIONS OF ANALOG ICS CARRIED OUT WITH STANDARD CAD TOOLS AND VERILOG-A

Jean-Christophe Krencker, Jean-Baptiste Kammerer, Yannick Hervé, Luc Hébrard, *InESS Strasbourg, France*

16:20 [57] MODELING OF THERMALLY INDUCED SKEW VARIATIONS IN CLOCK DISTRIBUTION NETWORK

Alessandro Sassone, Wei Liu, Andrea Calimera, Alberto Macii, Enrico Macii, Massimo Poncino, *Politecnico di Torino, Italy*

16:40-17:10 Coffee break

17:10-17:40 POSTER INTRODUCTION SESSION I

Chair: **Márta Rencz**, *Budapest Univ. of Technology and Economics, Hungary*

Posters are introduced by one slide in maximum 3 minutes each.

17:10 [11] THE INFLUENCE OF THE AMBIENT AND JUNCTION TEMPERATURE ON THE MPS CRITICAL PARAMETERS

Aneta Hapka, Włodzimierz Janke, *Koszalin Univ. of Technology, Poland*

17:13 [12] EXTENSION OF THE DELPHI METHODOLOGY TO DYNAMIC COMPACT THERMAL MODEL OF ELECTRONIC COMPONENT

Eric Monier-Vinard, Cheikh Tidiane Dia, Valentin Bissuel, Olivier Daniel, Julien Dufrenne, *Thales Corporate Services, France, Cheikh Tidiane Dia, Najib Laraqi, LTIE Avray, France*

17:16 [15] HEAT TRANSFER ENHANCEMENT IN IR TRANSPARENT MATERIALS

Dmitri Chestakov, J.H. Yu, *Philips Eindhoven, The Netherland*

17:19 [20] MEASUREMENT OF THE TIME-CONSTANT SPECTRUM: SYSTEMATIC ERRORS, CORRECTION

Vladimír Székely, *Mentor Graphics, Hungary, Albin Szalai*, *Budapest Univ. of Technology & Economics, Hungary*

17:22 [21] THERMAL ANALYSIS OF THE TYPE OF METAL DESIGN FOR LIGHT EMITTING DIODE

So Hyeon Mun, Jong Hwa Choi, *Myongji Univ., Korea, Moo Whan Shin*, *Yonsei Univ., Korea*

17:25 [22] LOCAL CONTROL OF SI/GE INTERFACE THERMAL RESISTANCE

Yann Chalopin, Sebastian Volz, *Ecole Centrale Paris, France, Gang Chen*, *MIT*

17:28 [24] CFD TRANSIENT MODEL OF THE NATURAL CONVECTION HEAT TRANSFER FOR AN HEAT SINK EFFECTS OF INCREASING SURFACE AND FINS SPACING

Carmine Sapia, Giorgio Sozio, *Univ. "Roma TRE", Italy*

17:31 [26] INVESTIGATION OF THE LOCAL SEEBECK COEFFICIENT OF METALLIC MATERIALS BY A SthM BASED TECHNIQUE

Mathieu Bardoux, *Univ. de Lyon, France, Xavier Kleber, Patrice Chantrenne, Séverine Gomès*, *INSA de Lyon, France*

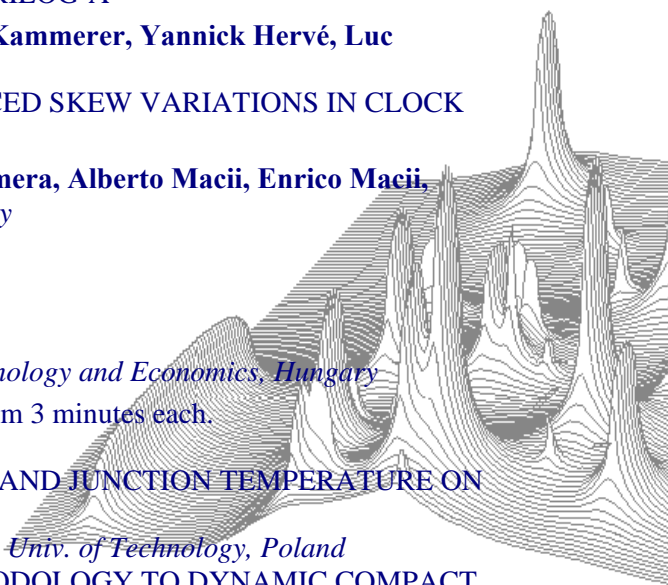
17:34 [27] ADVANCED THERMAL GROUND PLANE FOR MICROELECTRONICS

Jia Cai Oh, Nanyang, KingHo Li, SoonEng Ong, Kokfah Choo, *Technological Univ., Singapore*

17:37 [31] CONTRACTING CURRENT PATHS IN VANADIUM DIOXIDE THIN FILMS

Márton Bein, János Mizsei, *Budapest Univ. of Technology & Economics, Hungary*

17:40-18:10 Coffee break





18:10-18:40 **POSTER INTRODUCTION SESSION II**

Chair: **Márta Rencz**, *Budapest Univ. of Technology & Economics, Hungary*

Posters are introduced by one slide in maximum 3 minutes each.

18:10 [33] INFRARED IMAGING OF AN INTEGRATABLE, ROBUST THERMAL FLOW SENSOR WITH A THICK SILICON DIOXIDE MEMBRANE AND THROUGH-GOING SILICON HEAT CONDUCTORS

Kristoffer Palmer, Henrik Kratz, Hugo Nguyen, Greger Thornell, *Ångström Space Technology Centre Uppsala, Sweden*,

18:13 [39] THERMAL BEHAVIOR OF CRYSTALLINE THIN FILM SILICON SOLAR CELLS

Balázs Plesz, *Budapest Univ. of Technology and Economics, Hungary*

18:16 [42] FAST AND ACCURATE THERMAL SIMULATION AND MODELLING OF WORKLOADS OF MANY-CORE PROCESSORS

Bartosz Wojciechowski, Krzysztof Berezowski, Piotr Patronik, Janusz Biernat, *Wroclaw Univ. of Technology, Poland*

18:19 [43] THERMAL CHARACTERISATION OF NOVEL CRYSTALLINE SEMITRANSSPARENT SOLAR CELL

Enikő Bándy, Márta Rencz, *Budapest Univ. of Technology & Economics, Hungary*

18:22 [46] INVESTIGATING THERMAL PROPERTIES OF 980 NM GAAS PUMP LASER DIODES WITH A PULSED ELECTRICAL TECHNIQUE

El Gibari Mohammed, Yves Scudeller, *Univ. of Nantes, France*

18:25 [47] OPTICAL SPECTROSCOPY FOR THERMAL DIAGNOSTIC OF 980 NM GAAS PUMP LASER DIODES

El Gibari Mohammed, Yves Scudeller, *Univ. of Nantes, France*

18:28 [48] ELECTRO-THERMAL ANALYSIS OF IGBT MODULES WITHIN INVERTERS: EXPERIMENTS AND MODELING

Joe Antonios, Nicolas Ginot, Christophe Batard, Yves Scudeller, *Univ. of Nantes, France*

18:31 [51] OPTIMIZATION OF AN INFRARED SENSOR CARD FOR HARSH ENVIRONMENT PURPOSE

Gyula Horváth, György Bognár, *Budapest Univ. of Technology and Economics, Hungary*

18:34 [56] POWER CONSUMPTION AND TEMPERATURE MEASUREMENTS OF VIRTUALIZATION SOLUTIONS

Marius Marcu, Dacian Tudor, Sebastian Fuicu, *Politehnica Univ. of Timisoara, Romania*

18:37 [58] HOT SPOTS SUPPRESSION BY HIGH THERMAL CONDUCTIVITY FILM IN THIN-SUBSTRATE CHIPS FOR 3D-INTEGRATED LSI SYSTEMS

Fumiki Kato, Katsuya Kikuchi, Hiroshi Nakagawa, Masahiro Aoyagi, *National Institute of Advanced Industries of Science and Technology, Japan*

18:40-20:00 **Poster viewing/Cocktail**





WEDNESDAY 28 SEPTEMBER 2011

- 09:00-09:40 **INVITED TALK II: NANOPACK PROJECT**
Afshin Ziaei, *THALES Research & Technology, Palaiseau, France*
Chair: **Bernard Courtois**, *CMP, Grenoble, France*
- 09:40-11:00 **PACKAGE THERMAL ISSUES SESSION**
Chair: **Antonio Rubio**, *Univ. Politècnica de Catalunya, Spain*
- 09:40 [17] EVALUATION OF THERMAL TRANSIENT CHARACTERIZATION
METHODOLOGIES FOR HIGH-POWER LED APPLICATIONS
Stefan Müller, Thomas Zahner, Frank Singer, *OSRAM Opto Semiconductors, Germany*, **Gabriele Schrag, Gerhard Wachutka**, *Institute for Physics of Electrotechnology, Germany*
- 10:00 [9] THERMAL ANALYSIS OF THE OPEN TYPE OF LASER DIODE
Jong Hwa Choi, *Myong Ji Univ., Korea*, **Moo Whan Shin**, *Yonsei Univ., Korea*
- 10:20 [5] COMPARATIVE STUDY OF THE EFFECTS OF COALESCED AND
DISTRIBUTED SOLDER DIE ATTACH VOIDS ON THERMAL RESISTANCE OF
PACKAGED SEMICONDUCTOR DEVICE
Kenny Otiaba, R. S. Bhatti, N.N. Ekere, M. Ekpu, J. Adeyemi, *Univ. of Greenwich, UK*
- 10:40 [19] NUMERICAL STUDY OF A LIQUID METAL MINI-CHANNEL COOLER FOR
POWER SEMICONDUCTOR DEVICES
Mansour Tawk, Yvan Avenas, Afef Lebouc, M. Petit, *G2Elab, France*
- 11:00-11:30 Coffee break
- 11:30-12:30 **RELIABILITY SESSION I**
Chair: **Herming Chiueh**, *National Chiao Tung Univ., Taiwan*
- 11:30 [6] COMBINED AND ACCELERATED IN-SITU MEASUREMENT METHOD FOR
RELIABILITY AND AGING ANALYSES OF THERMAL INTERFACE
MATERIALS
Mohamad Abo Ras, Olaf Wittler, *Berliner Nanotest and Design GmbH, & Micro Materials Center Berlin e.V.*, **R. Haug, C. Monory-Plantier**, *Robert Bosch GmbH, Daniel May, TU Chemnitz*, **R. Schacht**, *Univ. of Applied Sciences Lausitz*, **Bernhard Wunderle, B. Michel**, *FhG Institute for Electronic Nano Systems, Chemnitz, Germany*
- 11:50 [3] ENHANCED PACKAGE- AND DIE-LEVEL DEFECT LOCALIZATION BY
DYNAMIC LOCK-IN THERMOGRAPHY
Rudolf Schlangen, Herve Deslandes, Randy Schussler, Ted Lundquist, *DCG Systems Fremont, USA* **Antoine Reverdy, Daniel Arias**, *Sector Technologies, France*
- 12:10 [28] EXPERIMENTAL AND NUMERICAL REINVESTIGATION FOR LIFETIME-
ESTIMATION OF PLATED THROUGH HOLES IN PRINTED CIRCUIT BOARDS
Torsten Nowak, Ralph Schacht, Hans Walter, Olaf Wittler, Klaus-Dieter Lang, *FhG Institute Reliability and Microintegration, Berlin*, **Bernhard Wunderle**, *FhG Institute for Electronic Nano Systems*, **Mohamad Abo Ras**, *Berliner Nanotest and Design GmbH, & Micro Materials Center Berlin e.V.*, **Daniel May, TU Chemnitz, Germany**
- 12:30-14:00 Lunch
- 14:00-15:40 **THERMINATOR SPECIAL SESSION II**
Chair: **Vadim Tsoi**, *Huawei Technologies, Sweden*
- 14:00 [50] IMPROVED POWER MODELING IN LOGI-THERMAL SIMULATION
András Timár, György Bognár, Márta Rencz, *Budapest Univ. of Technology & Economics, Hungary*
- 14:20 [23] A NOVEL SIMULATION ENVIRONMENT ENABLING MULTILEVEL
POWER ESTIMATION OF DIGITAL SYSTEMS



- 14:40 **Gergely Nagy, András Poppe**, *Budapest Univ. of Technology & Economics, Hungary*
[16] THERMAL MODELING OF 3D STACKS FOR FLOORPLANNING
Sven Reitz, Andy Heinig, Roland Martin, Jörn Stolle, Andreas Wilde, *FhG Institute for Integrated Circuits, Germany*
- 15:00 [60] HIGH TEMPERATURE CALIBRATION OF A COMPACT MODEL FOR GAN-ON-SI POWER SWITCHES
Steve Stoffels, Denis Marcon, Karen Geens, Xuanwu Kang, Geert Van Der Plas, Marleen Van Hove, Stefaan Decoutere, *IMEC, Belgium*
- 15:20 [38] SINGLE-CHIP CLOUD COMPUTER THERMAL MODEL
Mohammadsadegh Sadri, Andrea Bartolini, Luca Benini, *Univ. of Bologna, Italy*
- 15:40-16:10 Coffee break
- 16:10-16:50 **ADVANCED COOLING METHODS**
Chair: Bernhard Wunderle, *TU Chemnitz, Germany*
- 16:10 [53] COOLING OF NEXT GENERATION COMPUTER CHIPS: PARAMETRIC STUDY FOR SINGLE AND TWO-PHASE COOLING
Yassir Madhour, Jonathan Olivier, John Thome, *Ecole Polytechnique Fédérale de Lausanne, Switzerland*, **Severin Zimmermann, Dimos Poulidakos**, *ETH Zurich, Switzerland*, **Yassir Madhour, Severin Zimmermann, Bruno Michel**, *IBM Research, Switzerland*
- 16:30 [10] MODELING OF POWER DEVICES WITH DRIFT REGION INTEGRATED MICROCHANNEL COOLER
Kremena Vladimirova, Yvan Avenas, Jean-Christophe Crebier, Christian Schaeffer, Fabien Lebouc, Mansour Tawk, *G2Elab, France*
- 16:50-17:10 **VENDORS SESSION**
Chair: Bernard Courtois, *CMP, Grenoble, France*

16:50  , **Brieuc Turluche**

17:00  **www.cd-adapco.com, Ruben Bons**

17:10  , **Andras Vass-Varnai**

20:00 RESTAURANT LE PROCOPE

A dinner is organized at the restaurant Le Procope in Paris.

Le Procope is located in the heart of the Saint-Germain des Prés district.

Address:

13, rue de l'Ancienne Comédie
75006 PARIS



THURSDAY 29 SEPTEMBER 2011

09:00-10:00 RELIABILITY SESSION II

Chair: **Thomas Zahner**, *OSRAM, Germany*

09:00 [13] THERMAL CONTROL MECHANISM WITH IN-SITU TEMPERATURE SENSOR FOR TSV 3D-ICS

Po-Tsang Huang, Tzu-Ting Chiang, Herming Chiueh, Wei Hwang, *National Chiao-Tung Univ., Taiwan*

09:20 [30] EXTENSION OF THE SUNRED ALGORITHM FOR ELECTRO-THERMAL SIMULATION AND ITS APPLICATION IN FAILURE ANALYSIS OF LARGE AREA (ORGANIC) SEMICONDUCTOR DEVICES

László Pohl, Ernő Kollár, *Budapest Univ. of Technology and Economics, Hungary*

09:40 [49] EXECUTION FRAMEWORK MODEL FOR POWER-AWARE APPLICATIONS

Marius Marcu, Dacian Tudor, *Politehnica Univ. of Timisoara, Romania*

10:00-10:30 Coffee break

10:30-12:10 THERMAL CHARACTERIZATION AND MEASUREMENT SESSION

Chair: **Andrzej Napieralski**, *TU Lodz, Poland*

10:30 [36] IN-SITU ANALYSIS OF THERMAL PROPERTY OF POLYMER COMPOSITES BY EMBEDDED LED TEMPERATURE SENSOR

J.H. Yu, Dmitri Chestakov, Erik Eggink, *Philips Research, The Netherlands*

10:50 [52] CHARACTERIZATION OF SOLAR CELLS BY THERMAL TRANSIENT TESTING

Balázs Plesz, Gyula Horváth, András Vass-Várnai, *Budapest Univ. of Technology and Economics, Hungary*

11:10 [54] ACTIVE CONTROL OF CIRCUIT COOLING CONDITIONS FOR TRANSIENT THERMAL MEASUREMENT PURPOSES

Marcin Janicki, Zbigniew Kulesza, Tomasz Torzewicz, Andrzej Napieralski, *Technical Univ. of Lodz, Poland*

11:30 [29] MEASURING THE THERMAL CONDUCTIVITY OF THERMAL INTERFACE MATERIALS

Pierre-Olivier Chapuis, Lars Schneider, Damian Dudek, Nikolaos Kehagias, Michael Schmidt, Clivia Sotomayor Torres, *ICN, Spain*

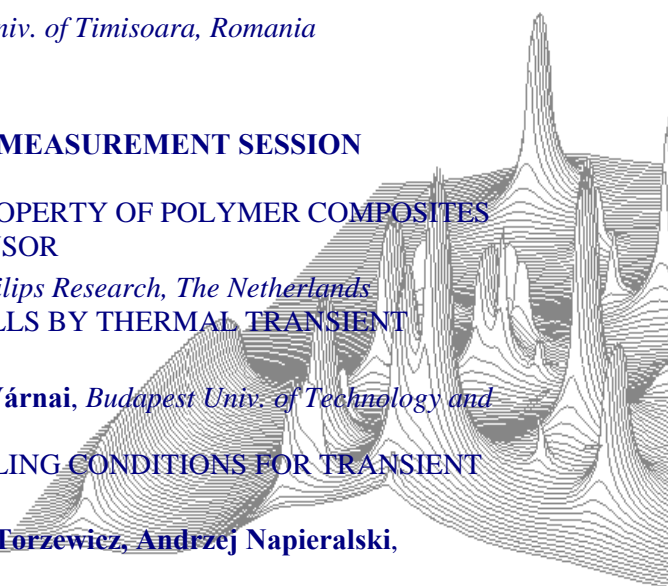
11:50 [25] THERMO-MECHANICAL DEFORMATION MEASUREMENT OF MICROWAVE HIGH POWER AMPLIFIER

Hubert Polaert, Philippe Eudeline, *Thales Air Systems, France*, **Dan Borza, Abdelkhalak Elhami**, *INSA de Rouen, France*, **Jean-Philippe Roux, Eric Larmet**, *CEVAA, France*

12:10-12:20 **CLOSING REMARKS**

Bernard Courtois, *CMP, Grenoble, France*

12:20-14:00 Lunch





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